

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

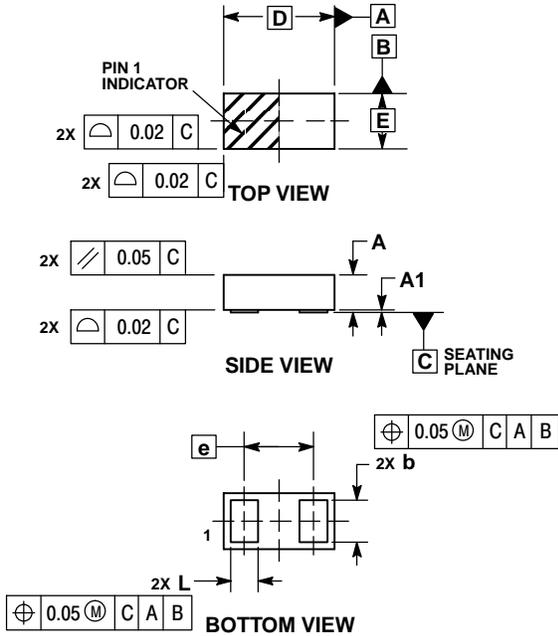
ON Semiconductor®



SCALE 16:1

DSN2, 0.435x0.23, 0.27P, (01005)  
CASE 152AK  
ISSUE A

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NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.

MILLIMETERS		
DIM	MIN	MAX
A	0.165	0.195
A1	---	0.030
b	0.177	0.193
D	0.435 BSC	
E	0.230 BSC	
e	0.270 BSC	
L	0.112	0.128

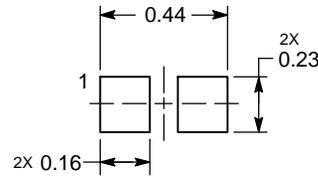
**GENERIC MARKING DIAGRAM\***



X = Specific Device Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present.

**RECOMMENDED SOLDER FOOTPRINT\***



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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NEW STANDARD:		
DESCRIPTION:	DSN2, 0.435X0.23, 0.27P (01005)	PAGE 1 OF 2

